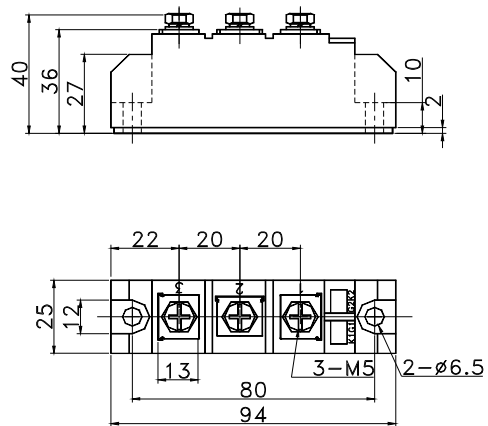
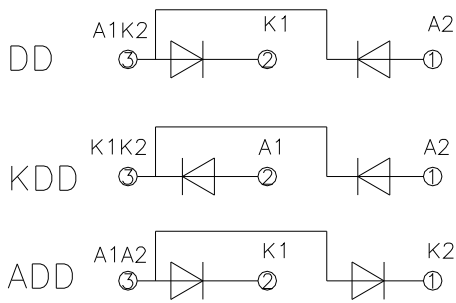


**DD110 ADD110 KDD110**

SYMBOL	CHARACTERISTIC	TEST CONDITIONS	T <sub>j</sub> (°C)	VALUE			UNIT
				Min	Type	Max	
I <sub>F(AV)</sub>	Mean forward current	180° half sine wave 50Hz Single side cooled, T <sub>C</sub> =100°C	150			110	A
I <sub>F(RMS)</sub>	RMS forward current	Single side cooled, T <sub>C</sub> =100°C	150			173	A
V <sub>RRM</sub>	Repetitive peak reverse voltage	V <sub>RRM</sub> tp=10ms V <sub>RSM</sub> = V <sub>DRM</sub> &V <sub>RRM</sub> +200V	150	600		1800	V
I <sub>RRM</sub>	Repetitive peak current	at V <sub>RRM</sub>	150			8	mA
I <sub>FSM</sub>	Surge forward current	10ms half sine wave	150			2.60	KA
I <sup>2</sup> t	I <sup>2</sup> T for fusing coordination	V <sub>R</sub> =0.6V <sub>RRM</sub>				34.4	A <sup>2</sup> s*10 <sup>3</sup>
V <sub>FO</sub>	Threshold voltage		150			0.80	V
r <sub>F</sub>	Forward slop resistance					1.74	mΩ
V <sub>FM</sub>	Peak forward voltage	I <sub>FM</sub> =330A	25			1.45	V
R <sub>th(j-c)</sub>	Thermal resistance Junction to heatsink	At 180° sine Single side cooled				0.350	°C /W
V <sub>iso</sub>	Isolation voltage	50Hz,R.M.S,t=1min, I <sub>iso</sub> :1mA(max)		2500			V
F <sub>m</sub>	Terminal connection torque(M5)					2.0	N·m
	Mounting torque(M6)					3.0	N·m
T <sub>stg</sub>	Stored temperature			-40		125	°C
W <sub>t</sub>	Weight					160	g
Outline	202F3						

**OUTLINE DRAWING & CIRCUIT DIAGRAM**



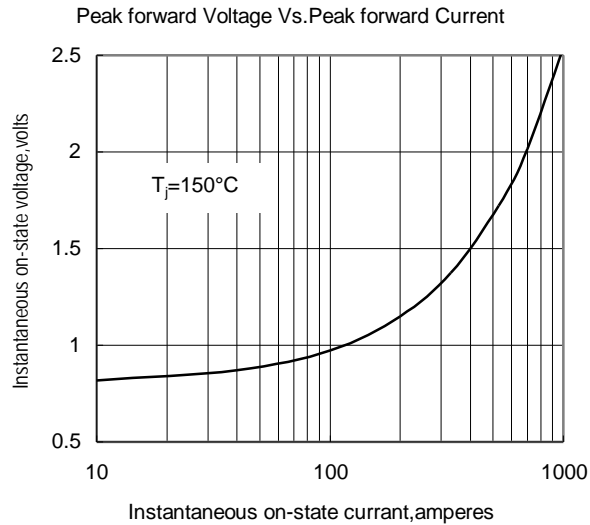


Fig.1

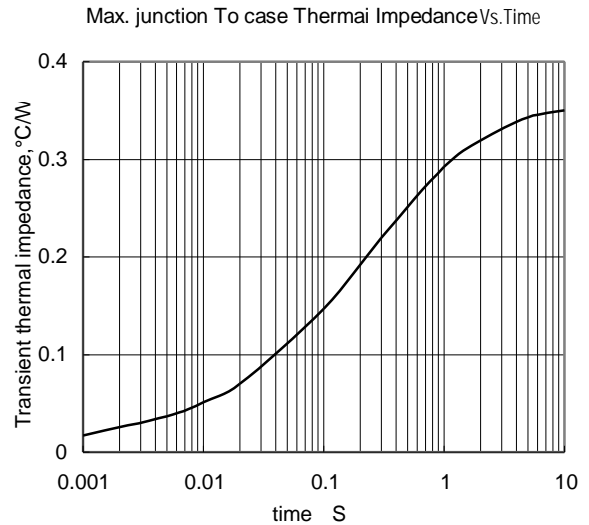


Fig.2

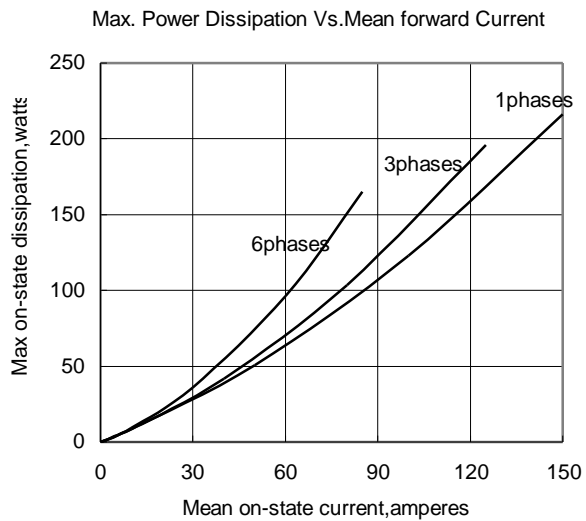


Fig.3

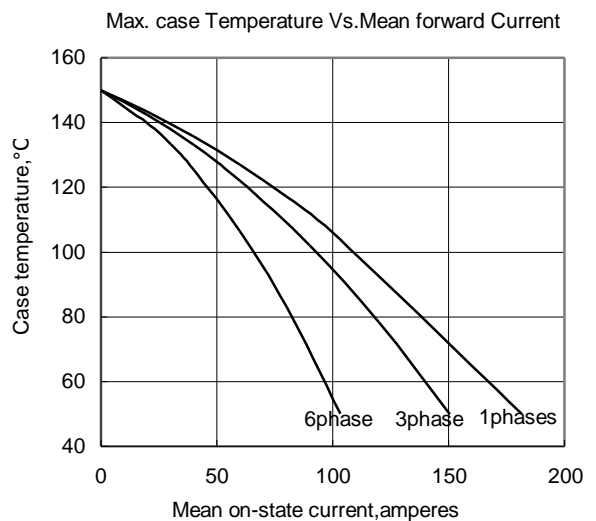


Fig.4

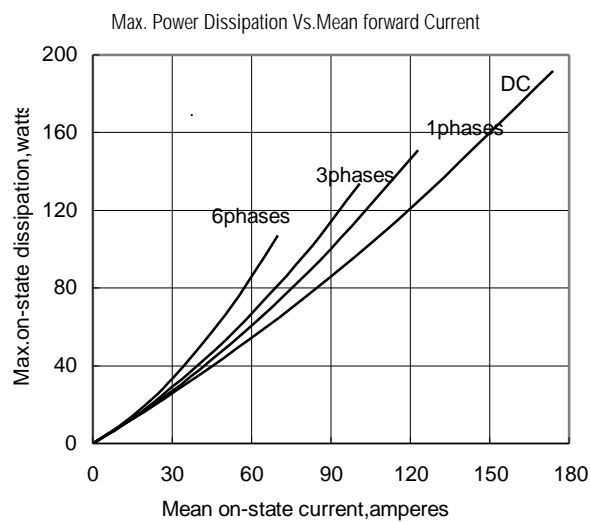


Fig.5

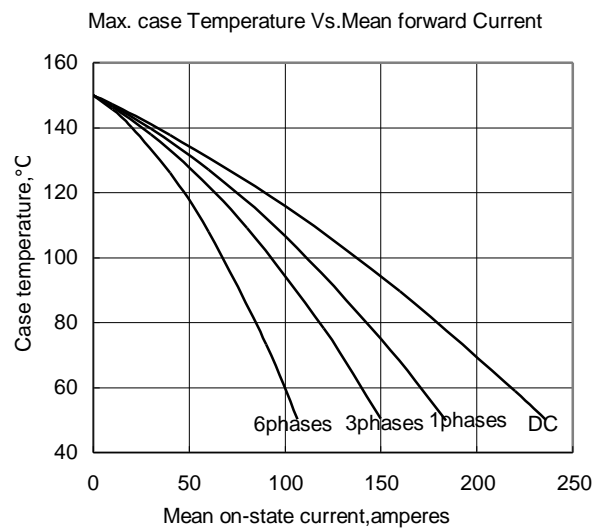


Fig.6